

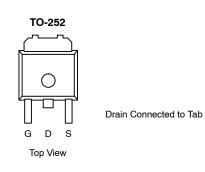
### D110NH02L-VB Datasheet

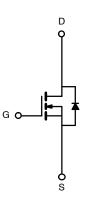
## N-Channel 20-V (D-S)175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
20	0.0045 @ $V_{GS}$ = 4.5 V	100		
20	0.006 @ V <sub>GS</sub> = 2.5 V	90		

#### **FEATURES**

- Trench Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R<sub>g</sub> Tested





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	20	v		
Gate-Source Voltage		V <sub>GS</sub>	±15	V		
	$T_{C} = 25^{\circ}C$		100			
Continuous Drain Current <sup>a</sup>	$T_{C} = 100^{\circ}C$	- I <sub>D</sub>	80			
Pulsed Drain Current		I <sub>DM</sub>	200	— A		
Continuous Source Current (Diode Conduction) <sup>a</sup>		IS	65			
	$T_{C} = 25^{\circ}C$		71			
Maximum Power Dissipation	T <sub>A</sub> = 25°C	P <sub>D</sub>	8.3 <sup>b, c</sup>	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
	$t \le 10$ sec.		15	18	°C/W		
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	40	50			
Maximum Junction-to-Case	•	R <sub>thJC</sub>	1.75	2.1			

Notes

a. Package Limited

b. Surface Mounted on 1" x 1" FR4 Board

c.  $t \leq 10 \text{ sec}$ 

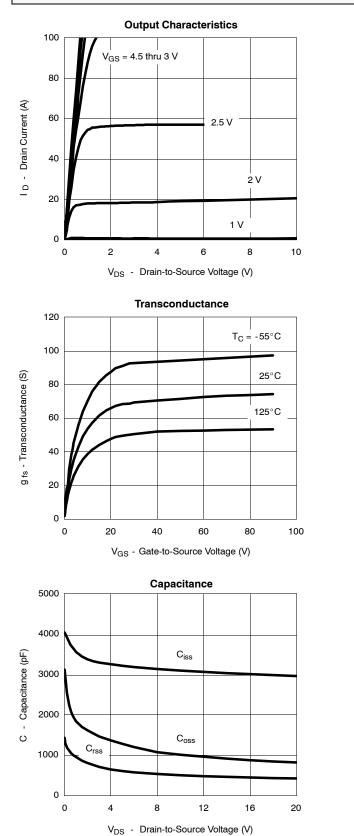
Parameter	Symbol	Test Condition		Тур <sup>а</sup>	Max	Unit	
Static			•				
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	0.5		1.5	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = $\pm$ 12 V			±100	nA	
		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 $^{\circ}$ C			50		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS}$ = 5 V, $V_{GS}$ = 4.5 V	100			А	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0045		Ω	
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125°C		0.0055			
		$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.006		-	
Forward Transconductanceb	9fs	$V_{DS} = 5 V, I_{D} = 40 A$	20			S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			3660		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 20 V, f = 1 MHz		730			
Reverse Transfer Capacitance	C <sub>rss</sub>			375			
Total Gate Charge <sup>c</sup>	Qg			26	35	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $~V_{GS}$ = 4.5 V, $I_{D}$ = 40 A		5			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		1	
Gate Resistance	Rg	1			3.7	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	35		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 0.25 $\Omega$		120	190	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 40$ Å, $V_{GEN} = 4.5$ V, $R_G = 2.5 \Omega$		45	70		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	35		
Source-Drain Diode Ratings an	d Characteristi	c (T <sub>C</sub> = 25°C)					
Pulsed Current	I <sub>SM</sub>				100	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_{F}$ = 100 A, $V_{GS}$ = 0 V		1.2	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>			70	ns		

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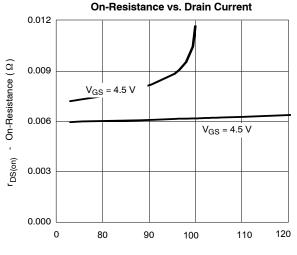


#### TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

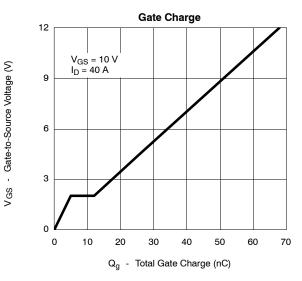


100 80 I D - Drain Current (A) 60 40  $T_C = 125^{\circ}C$ 20 25°C -55°C 0 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 V<sub>GS</sub> - Gate-to-Source Voltage (V)

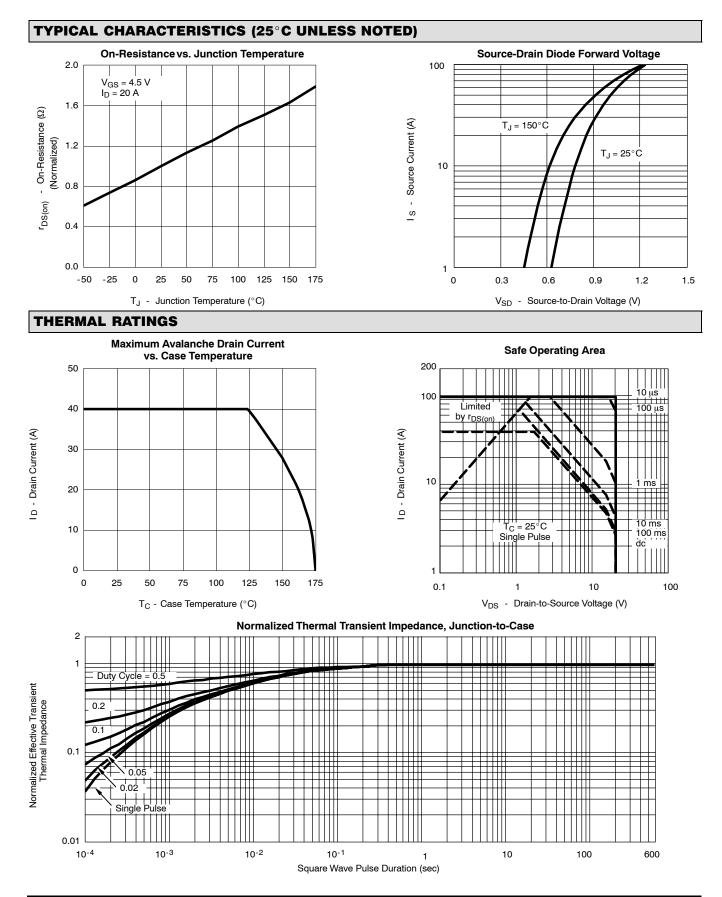
**Transfer Characteristics** 





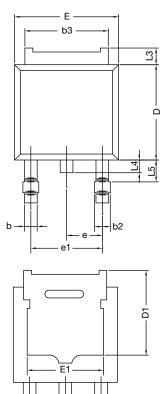


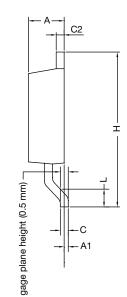






## **TO-252AA CASE OUTLINE**





	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090 BSC			
e1	4.56 BSC		BSC 0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

Note

• Dimension L3 is for reference only.



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